

LP-NSM005

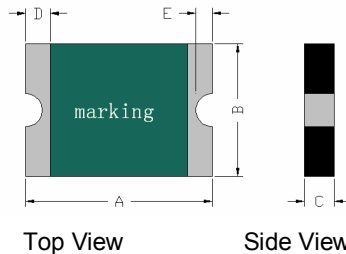
Features

- Small size of 1206
- Lead-free and compliant with the European Union RoHS Directive 2011/65/EU
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly



Product Dimensions (mm)

Part number	A Max.	B Max.	C Max.	D Min.	E Min.
LP-NSM005	3.50	1.80	0.85	0.10	0.20

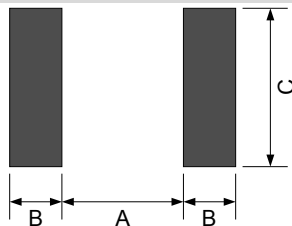


Electrical Characteristics

Part number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} Current(A) Time(S)	$P_{d\ typ}$ (W)	R_{min} (Ω)	R_{1max} (Ω)
LP-NSM005	0.05	0.15	60	10	1.0 1.2	0.6	2.00	50.00

I_H =Hold current: maximum current at which the device will not trip at 25°C still air.
 I_T =Trip current: minimum current at which the device will always trip at 25°C still air.
 V_{max} =Maximum voltage device can withstand without damage at rated current.
 I_{max} =Maximum fault current device can withstand without damage at rated voltage.
 T_{trip} =Maximum time to trip(s) at assigned current.
 $P_{d\ typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min} =Minimum device resistance at 25°C prior to tripping.
 R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-NSM005	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase, hot air oven.
 * Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

Package Information

Tape & Reel: 4000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

Specifications are subject to change without notice.

